



CALL FOR PAPERS



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

IEEE TRANSACTIONS ON COMPONENTS AND PACKAGING TECHNOLOGIES

A Special Section on **Electronic Part Obsolescence**

Manuscript Due Date: **June 15, 2007**

The electronic industries' ability to sustain Moore's Law has transformed our world and many product sectors thrive on the rapid rate of technology change, however, there are a growing number of critical systems for which the rapid rate of technology change is a nightmare not an opportunity.

Driven by the consumer electronics product sector, newer and better electronic components are being introduced frequently, rendering older components obsolete. Yet, systems such as aircraft avionics, military system, communications infrastructure, and industrial equipment, which are often produced for many years and sustained for many decades, suffer the consequences of electronic part obsolescence because they have no control over their electronic part supply chain due to their low production volumes.

This **Special Section** in the *IEEE Transactions on Components and Packaging Technologies* will survey state-of-the-art research in the electronic part obsolescence area (also known as DMSMS - Diminishing Manufacturing Sources and Material Shortages). Topics of interest include, but are not limited to:

- Electronic part obsolescence date/risk forecasting
- Alternative/substitute part identification
- Electronic part obsolescence mitigation approaches:
 - Lifetime and bridge buys
 - Part emulation
 - Thermal uprating of parts
 - Salvaged (reclaimed) parts
 - Aftermarket supplied parts
 - Reverse engineering of legacy parts
- Migration to lead-free parts
- Counterfeit parts
- Material risk index calculations for part insertion
- Electronic part qualification and testing
- Electronic system refresh/redesign methodologies

All manuscripts will be peer-reviewed and should be submitted to the Guest Editors before **June 15, 2007**. To discuss a potential manuscript, please call or email the Guest Editors. Each manuscript is expected to be 12 to 18 double-spaced pages (plus Figures and Tables), and should be submitted as a word processor or PDF file. The lead author should include full address, phone, FAX and Email address, to aid in communication. More details for preparation are provided on our website: <http://www.cpmt.org/trans/trans-cpt.html>.

Guest Editors:

Dr. Peter Sandborn
CALCE, Dept. of Mechanical Engineering
University of Maryland
College Park, MD 20742
Ph: 301-405-3167
Email: sandborn@calce.umd.edu

Ric Loeslein
NAVAIR Aging Aircraft IPT
22347 Cedar Point Rd., Bldg. 2185, Rm. 2100 C-4
Patuxent River, MD 20670
Ph: 301-342-2179
Email: george.loeslein@navy.mil